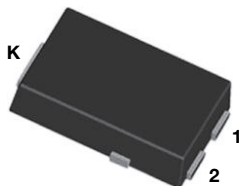


# High Current Density Surface-Mount TMBS® (Trench MOS Barrier Schottky) Rectifier

Ultra Low  $V_F = 0.54 \text{ V}$  at  $I_F = 6 \text{ A}$

## eSMP® Series



SMPC (TO-277A)



## LINKS TO ADDITIONAL RESOURCES



## FEATURES

- Very low profile - typical height of 1.1 mm
- Trench MOS Schottky technology
- Low forward voltage drop, low power losses
- High efficiency operation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available  
- Automotive ordering code; base P/NHM3
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters, and polarity protection applications.

## MECHANICAL DATA

**Case:** SMPC (TO-277A)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meets JESD 201 class 2 whisker test

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	12.0 A
$V_{RRM}$	150 V
$I_{FSM}$	200 A
$V_F$ at $I_F = 12.0 \text{ A}$ ( $T_J = 125 \text{ °C}$ )	0.62 V
$T_J$ max.	175 °C
Package	SMPC (TO-277A)
Circuit configuration	Single

## MAXIMUM RATINGS ( $T_A = 25 \text{ °C}$ unless otherwise noted)

PARAMETER	SYMBOL	V12PM153	UNIT
Device marking code		12MP	
Maximum repetitive peak reverse voltage	$V_{RRM}$	150	V
Maximum average forward rectified current (fig. 1)	$I_F^{(1)}$	12.0	A
	$I_F^{(2)}$	3.7	
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	$I_{FSM}$	200	A
Operating junction temperature range	$T_J^{(3)}$	-40 to +175	°C
Storage temperature range	$T_{STG}$	-55 to +175	°C

## Notes

(1) Mounted on 30 mm x 30 mm pad areas aluminum PCB

(2) Free air, mounted on recommended copper pad area

(3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 6.0 A	T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.67	-	V
	I <sub>F</sub> = 12.0 A			0.79	0.85	
	I <sub>F</sub> = 6.0 A	T <sub>J</sub> = 125 °C		0.54	-	
	I <sub>F</sub> = 12.0 A			0.62	0.68	
Reverse current	V <sub>R</sub> = 100 V	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	0.001	-	mA
		T <sub>J</sub> = 125 °C		2	-	
Reverse current	V <sub>R</sub> = 150 V	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	0.15	mA
		T <sub>J</sub> = 125 °C		4.2	12	
Typical junction capacitance	4.0 V, 1 MHz		C <sub>J</sub>	820	-	pF

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

PARAMETER	SYMBOL	V12PM153	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)(2)}$	75	$^{\circ}\text{C/W}$
	$R_{\theta JM}^{(3)}$	4	

**Notes**(1) The heat generated must be less than the thermal conductivity from junction to ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ (2) Free air mounted on recommended copper pad area; thermal resistance  $R_{\theta JA}$  - junction to ambient(3) Mounted on 30 mm x 30 mm aluminum PCB; thermal resistance  $R_{\theta JM}$  - junction to mount**ORDERING INFORMATION** (Example)

PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
V12PM153-M3/H	0.10	H	1500	7" diameter plastic tape and reel
V12PM153-M3/I	0.10	I	6500	13" diameter plastic tape and reel
V12PM153HM3/H <sup>(1)</sup>	0.10	H	1500	7" diameter plastic tape and reel
V12PM153HM3/I <sup>(1)</sup>	0.10	I	6500	13" diameter plastic tape and reel

**Note**

(1) AEC-Q101 qualified

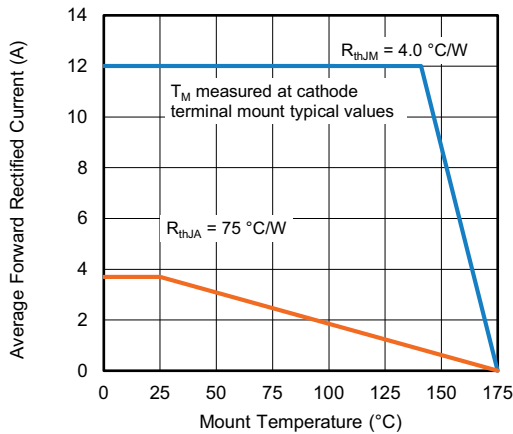
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Forward Current Derating Curve

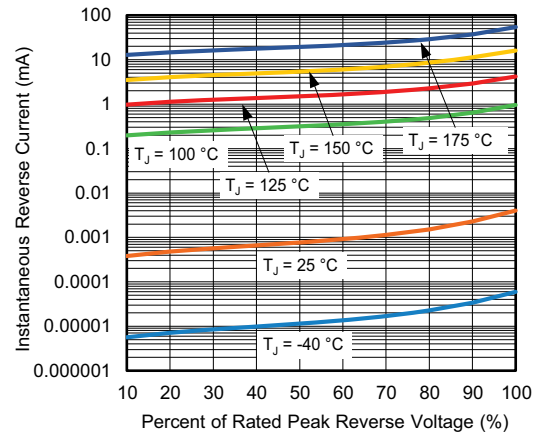


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

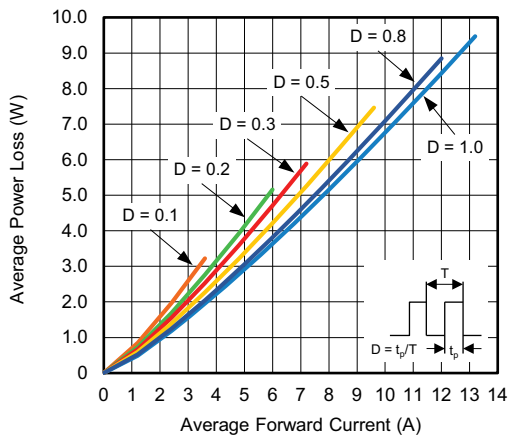


Fig. 2 - Forward Power Loss Characteristics

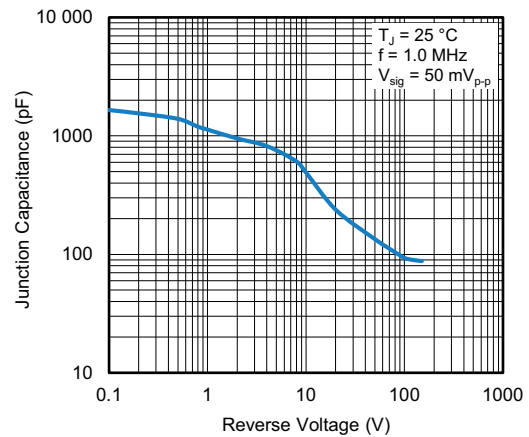


Fig. 5 - Typical Junction Capacitance

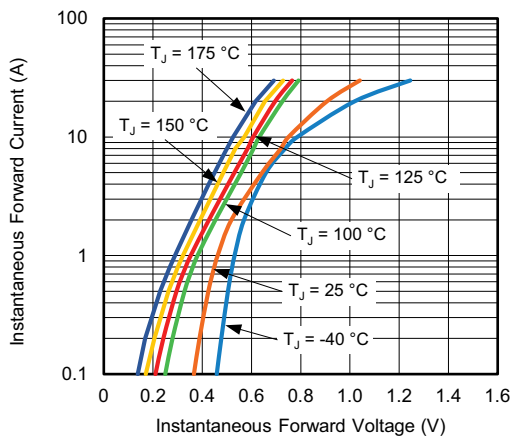


Fig. 3 - Typical Instantaneous Forward Characteristics

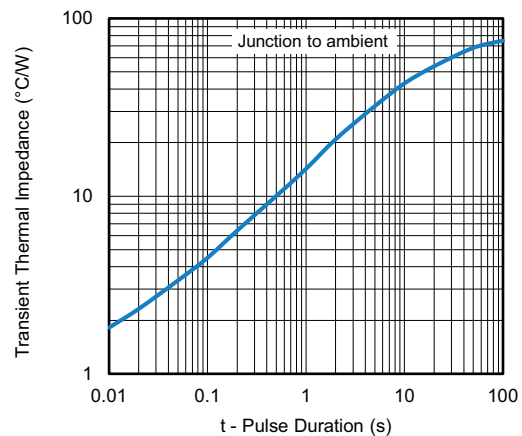
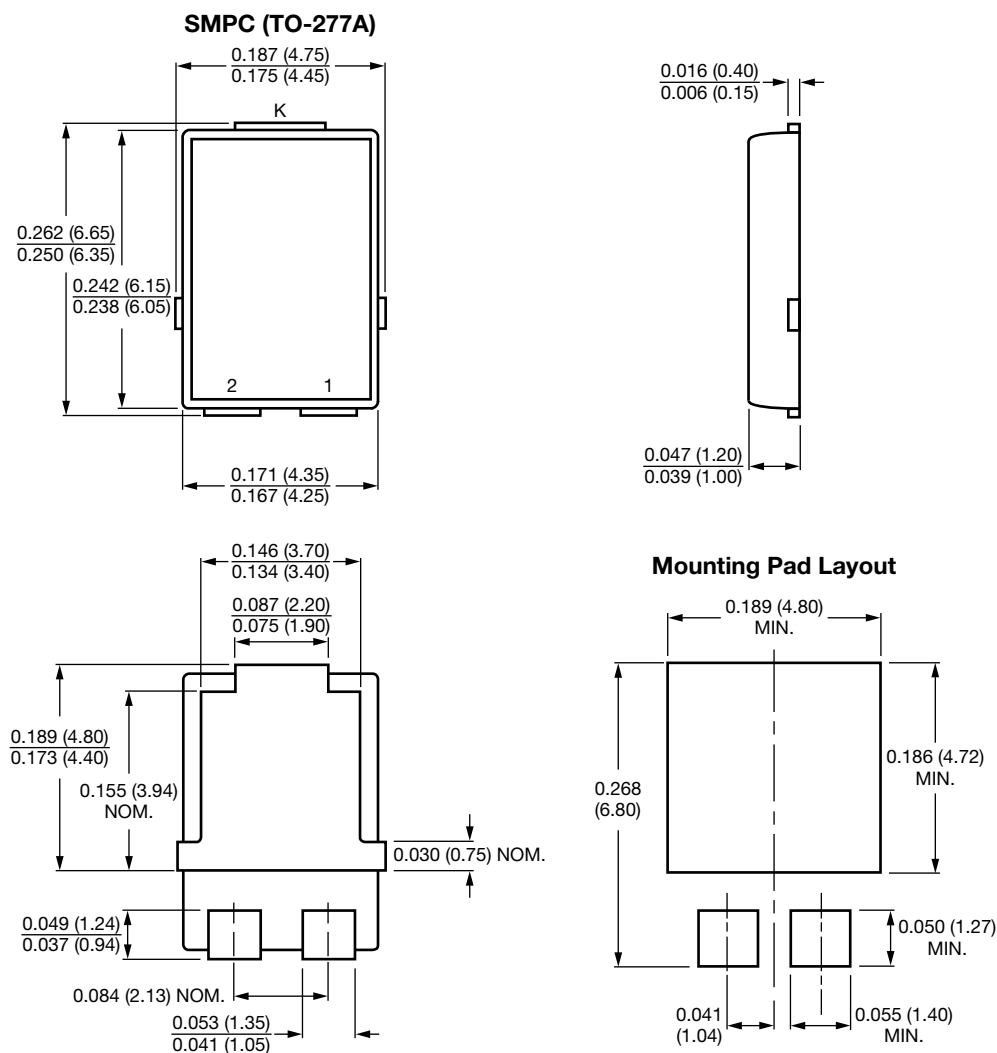


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

Conform to JEDEC® TO-277A



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